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Renesas Technology Corp. Customer Support Dept. April 1, 2003



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1-of-8-line Data Selector/Multiplexer

www.DataSheet4U.com



ADE-205-450 (Z) 1st. Edition Sep. 2000

Description

This data selector/multiplexer contains full-on-chip binary decoding to select the desired data source. The HD74HC152 selects one-of-eight data sources.

Features

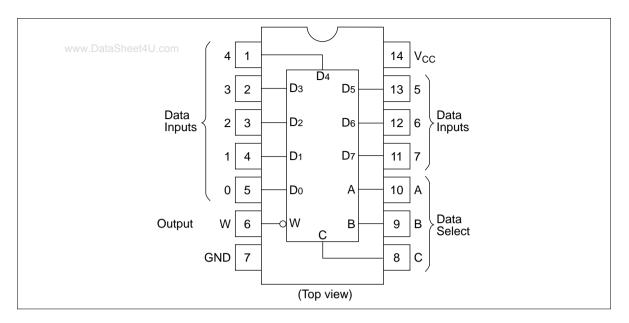
- High Speed Operation: t_{pd} (Any D to W) = 17 ns typ ($C_L = 50 \text{ pF}$)
- High Output Current: Fanout of 10 LSTTL Loads
- Wide Operating Voltage: $V_{CC} = 2 \text{ to } 6 \text{ V}$
- Low Input Current: 1 µA max
- Low Quiescent Supply Current: I_{CC} (static) = 4 μ A max (Ta = 25°C)

Function Table

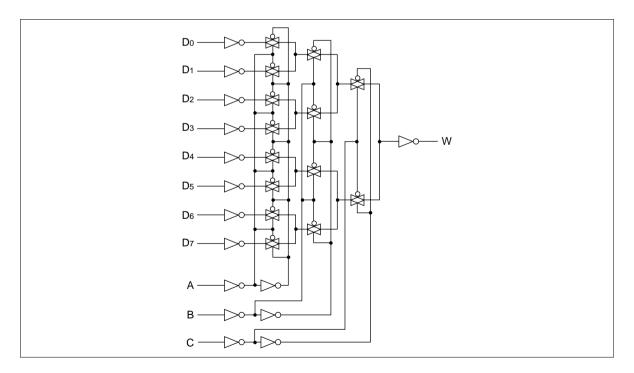
| Select | inputs | | Output | Select | Output | | |
|--------|--------|---|--------------------|--------|--------|---|--------------------|
| С | В | Α | w | С | В | Α | W |
| L | L | L | \overline{D}_{o} | Н | L | L | \overline{D}_4 |
| L | L | Н | \overline{D}_1 | Н | L | Н | \overline{D}_{5} |
| L | Н | L | \overline{D}_2 | Н | Н | L | \overline{D}_6 |
| L | Н | Н | \overline{D}_{3} | Н | Н | Н | \overline{D}_7 |

Note: D_0 to D_7 : the level of the D respective input

Pin Arrangement



Logic Diagram



DC Characteristics

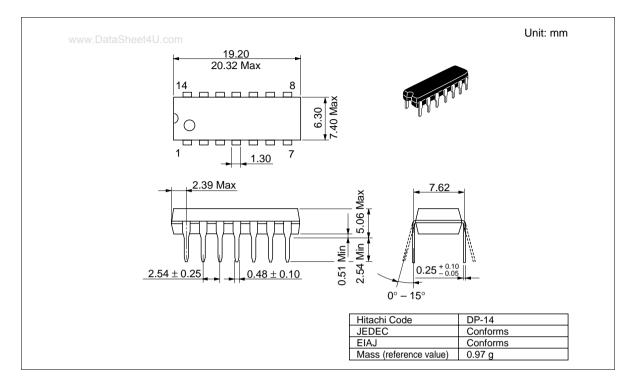
| www.DataSheet4U.com | | Ta = 25°C | | Ta = −40 to +85°C | | | | | |
|--------------------------|-----------------|---------------------|------|----------------------|------|------|------|------|---|
| Item | Symbol | V _{cc} (V) | Min | Тур | Max | Min | Max | Unit | Test Conditions |
| Input voltage | V _{IH} | 2.0 | 1.5 | | | 1.5 | _ | V | |
| | | 4.5 | 3.15 | — | — | 3.15 | — | | |
| | | 6.0 | 4.2 | | — | 4.2 | — | _ | |
| | V _{IL} | 2.0 | | | 0.5 | — | 0.5 | V | |
| | | 4.5 | | _ | 1.35 | _ | 1.35 | _ | |
| | | 6.0 | | | 1.8 | — | 1.8 | _ | |
| Output voltage | V _{OH} | 2.0 | 1.9 | 2.0 | | 1.9 | — | V | Vin = V _{IH} or V _{IL} I_{OH} = -20 μ A |
| | | 4.5 | 4.4 | 4.5 | | 4.4 | — | _ | |
| | | 6.0 | 5.9 | 6.0 | _ | 5.9 | — | _ | |
| | | 4.5 | 4.18 | | | 4.13 | — | _ | $I_{OH} = -4 \text{ mA}$ |
| | | 6.0 | 5.68 | | | 5.63 | — | _ | I _{OH} = -5.2 mA |
| | V _{OL} | 2.0 | | 0.0 | 0.1 | — | 0.1 | V | Vin = V _{IH} or V _{IL} I_{OL} = 20 μ A |
| | | 4.5 | | 0.0 | 0.1 | — | 0.1 | _ | |
| | | 6.0 | | 0.0 | 0.1 | — | 0.1 | _ | |
| | | 4.5 | | | 0.26 | — | 0.33 | _ | $I_{OL} = 4 \text{ mA}$ |
| | | 6.0 | | | 0.26 | — | 0.33 | _ | $I_{oL} = 5.2 \text{ mA}$ |
| Input current | lin | 6.0 | | | ±0.1 | | ±1.0 | μΑ | $Vin = V_{cc} \text{ or } GND$ |
| Quiescent supply current | I _{cc} | 6.0 | — | | 4.0 | — | 40 | μΑ | Vin = V_{cc} or GND, lout = 0 μ A |

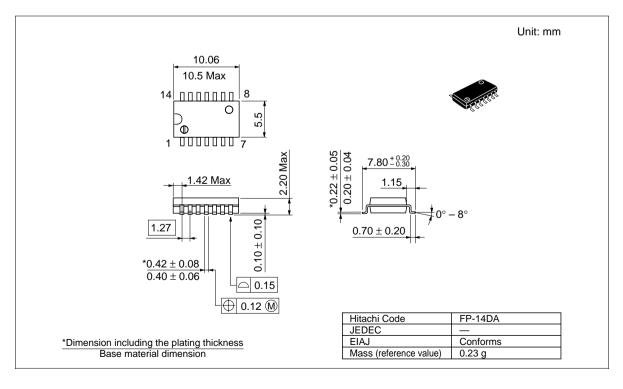


AC Characteristics ($C_L = 50 \text{ pF}$, Input $t_r = t_f = 6 \text{ ns}$)

| | | | Ta = | : 25°C | ; | Ta = - +85°C | -40 to | | |
|-------------------|------------------|--------------|------|--------|-----|-----------------|--------|------|-----------------|
| www.DataSh | Symbol | V_{cc} (V) | Min | Тур | Max | Min | Max | Unit | Test Conditions |
| Propagation delay | t _{PLH} | 2.0 | _ | _ | 160 | _ | 200 | ns | A, B or C to W |
| time | t _{PHL} | 4.5 | _ | 17 | 32 | — | 40 | | |
| | | 6.0 | | _ | 27 | — | 34 | - | |
| | | 2.0 | | | 150 | _ | 190 | = | Any D to W |
| | | 4.5 | | 15 | 30 | _ | 38 | = | |
| | | 6.0 | | | 26 | _ | 33 | = | |
| Output rise/fall | t _{TLH} | 2.0 | | | 75 | _ | 95 | ns | |
| time | t_{THL} | 4.5 | | 5 | 15 | — | 19 | - | |
| | | 6.0 | | _ | 13 | — | 16 | = | |
| Input capacitance | Cin | | | 5 | 10 | | 10 | pF | |

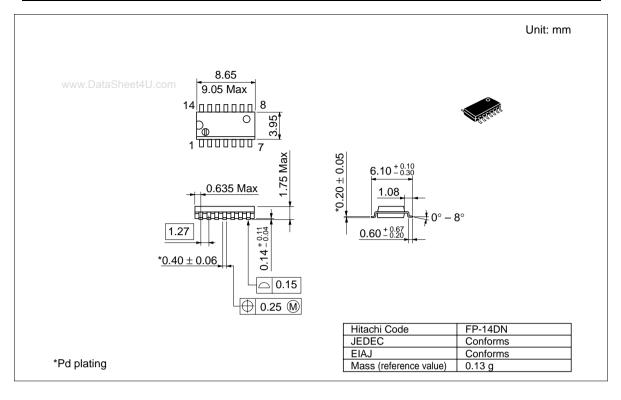
Package Dimensions







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